

Minutes  
Multi-Gigabit Optical Automotive Ethernet (OMEGA)  
Task Force Plenary  
30 November 2021

Attendance list as recorded in Webex participant list

Last Name	First Name	Employer	Affiliations	November 30th
Abbott	John	Corning	Corning	X
Akin	Sami	Volkswagen AG	Volkswagen AG	
Amamiya	Yasushi	MegaChips	MegaChips	
Andrae	Stefan	SEI Antech-Europe GmbH	SEI Antech-Europe GmbH	
Aono	Michikazu	Yazaki	Yazaki	
Akin	Sami	VW AG	VW AG	
Araki	Nobuyasu	Yazaki	Yazaki	
Beaudoin	Denis	TI	TI	
Bergner	Bert	TE Connectivity	TE Connectivity	
Boyer	Rich	APTIV	APTIV	
Barbero	Fernando	KDPOF	KDPOF	X
Bordogna	Mark	Intel	Intel	
Borda	Jamila	BMW	BMW	
Brooks	Paul	Viavi Solutions	Viavi Solutions	
Brown	Blake	UNH-IOL	UNH-IOL	
Bruckman	Leon	Huawei	Huawei	
Brychta	Michal	Analog Devices	Analog Devices	
Castrillon	Alejandro	Marvell	Marvell	
Castro	Jose	Panduit	Panduit	
Chang	Ayla			
Chang	Jae-yong	Keysight	Keysight	X
Choudhury	Mabud	OFS	OFS	
Chuang	Keng Hua	HPE	HPE	
Cuesta	Emilio	TE Connectivity	TE Connectivity	
D'Ambrosia	John	Futurewei	Futurewei	X
Dawson	Fred	Ch		
DiBiao	Eric	TE Connectivity	TE Connectivity	
Dittmann	Markus	KDPOF	KDPOF	X
Donthu	Suresh	Corning	Corning	
Dube	Kae	UNH-IOL	UNH-IOL	
Eek	Magnus	Volvo Cars	Volvo Cars	
Felgenhauer	Alexander	Yazaki	Yazaki	
Fellhauer	Felix	Bosch	Bosch	
Ferretti	Vincent	Corning	Corning	
Fortusini	David	Corning	Corning	
Fukuoka	Takashi	AutoNetworks Technologies Ltd.	AutoNetworks Technologies Ltd.; Sumitomo Electric Industries, Ltd.	X
Gao	Xiangong			
Gao	Sharon	Huawei	Huawei	
Gharba	Ahmed	Volvo Car Corp.	Volvo Car Corp.	
Giovanne	Laura	Broadcom	Broadcom	
Glanzner	Martin	SEI Antech-Europe GmbH	SEI Antech-Europe GmbH	
Gomez	Chisato	Nitto Denko Corporation	Nitto Denko Corporation	X
Goto	Hideki	Toyota Motor Corporation	Toyota Motor Corporation	X
Grow	Robert	Robert M. Grow Consulting	RMG Consulting, KDPOF	X
Guangcan	Mi	Huawei	Huawei	
Haasz	Jodi	IEEE-SA	IEEE-SA	X
Hajduczenia	Marek	Charter Communications	Charter Communications	

Harshbarger	Douglas	Corning Incorporated	Corning Incorporated	X
Hartmann	Stephan	Siliconally GmbH	Siliconally GmbH	
Hayashi	Takehiro	HAT Labs	HAT Labs	X
He	Xiang	Huawei	Huawei	
HIRASE	Hidenari	AGC	AGC	X
Horrmeier	Bernd	Phoenix Contact	Phoenix Contact	
Huang	David	Broadcom	Broadcom	
Huang	Shaowu	Marvell	Marvell	
Hyakudai	Toshihisa	Sony	Sony	
Hyakutake	Yasuhiro	Adamant Namiki Precision Jewel	Adamant Namiki Precision Jewel	X
Ikeda	Teppei	Denso	Denso	
Ingham	Jonathan	Huawei	Huawei	
Isono	Hideki	FOC	FOC	X
Jackson	Ken	Sumitomo	Sumitomo	
Jiménez	Andy	WESCO	WESCO	
Kadry	Haysam	Ford Motor Company	Ford Motor Company	X
KAGAMI	Manabu	NI Tech	NI Tech	X
Kazuhiko	Ishibe	Anritsu	Anritsu	
Kamino	John	OFS	OFS	X
Kawahara	Keisuke	Furukawa Electric	Furukawa Electric	X
KIKUTA	Tomohiro	Adamant Namiki Precision Jewel	Adamant Namiki Precision Jewel	X
Kim	Joshua	Hirose USA	Hirose USA	
King	Roger	TRUMPF Photonic Components	TRUMPF Photonic Components	X
Kintingham	Alan	I-PEX	I-PEX	
Kobayashi	Shigeru	AIO Core	AIO Core	X
Koependoerfer	Erwin	Leoni	Leoni	
Kondo	Taiji	MegaChips	MegaChips	X
Kota	Kishore	Marvell	Marvell	
Kumadayazaki	Taketo			
Kurashima	Kazuyoshi	AGC	AGC	X
Lackner	Hans	QoSCom GmbH	QoSCom GmbH	
Law	David	HPE	HPE	X
Lewis	David	Lumentum	Lumentum	
LI	Tobey	MediaTek	MediaTek	
Liu	Karen	Lightwave	Lightwave	
Lee	Bernard	Senko	Senko	
Lee	Sylvanus	Leviton	Leviton	
Lingle	Robert	OFS	OFS	
Maguire	Valerie	Siemon	Siemon	
Malicoat	David	Malicoat Networking Solutions	Senko Advanced Components	X
Mark	Simon	Wurth	Wurth	
Martino	Kjersti	Inneos	Inneos	X
Marques	Flavio	Furukawa electric	Furukawa Electric	
Masuda	Takeo	OITDA/PETRA	OITDA/PETRA	
Matheus	Kirsten	BMW	BMW	
McMillan	Larry	Western Digital	Western Digital	
Mueller	Harald	Endress + Hauser	Endress + Hauser	
Mueller	Thomas	Rosenberger	Rosenberger	
Murty	Ramana	Broadcom	Broadcom	X
Nakagawa	Hideki	AGC	AGC	
Neulinger	Christian	MD Elektronik	MD Elektronik	
New	Anthony	Prysmian Group	Prysmian Group	X
Nicholl	Gary	Cisco	Cisco	
Nikolich	Paul	802 Chairman	802 Chairman	X
Niihara	Yoshihiro	Fujikura	Fujikura	X
Ogura	Ichiro	Petra	Petra	X

Omori	Kumi	NEC	NEC	
Ortiz	David	KDPOF	KDPOF	
Pandey	Sujan	Huawei	Huawei	
Pankert	Joseph	TRUMPF Photonic Components	TRUMPF Photonic Components	
Pardo	Carlos	KDPOF	KDPOF	X
Parsons	Earl	Commscope	Commscope	
Peng	Semmy	Huawei	Huawei	
Pérez-Aranda	Rubén	KDPOF	KDPOF	X
Peteranderl	Ralf	Rosenberger	Rosenberger	
Petrarca	Ryan	TDK	TDK	
Pham	Phong	EastPoint	EastPoint	
Piehler	David	Dell	Dell	
Pimpinella	Rick	Panduit	Panduit	X
Pinzón	Plinio	KDPOF	KDPOF	
Pitwon	Richard	Resolute Photonics	Resolute Photonics	X
Powell	William	Independent	Independent	
Preis	Roland	MD Elektronik	MD Elektronik	X
Regev	Alon	Keysight	Keysight	
Reinhard	Michael	SEI Antech-Europe GmbH	SEI Antech-Europe GmbH	
Ren	Hao	Huawei	Huawei	
Retting	Thomas	Beckhoff Automation	Beckhoff Automation	
Rush	Joshua	UNH-IOL	UNH-IOL	
Sambasivan	Sam	AT&T	AT&T	
Sakai	Toshiaki	Socionext	Socionext	
Savi	Olindo	Hubbell Incorporated	Hubbell Incorporated	
Sawano	Hiroshi	OITDA		
Sayre	Edward	Samtec	Samtec	
Schmalzigaug	Thomas	HUBER+SUHNER	HUBER+SUHNER	
Shukla	Priyank	Synopsys	Synopsys	
Shigematsu	Masayuki	Sumitomo Electric	Sumitomo Electric	
Shiino	Masato	Furukawa Electric	Furukawa Electric	X
Shubochkin	Roman	OFS	OFS	
Shukla	Priyank	Synopsys	Synopsys	
Silvano de Sousa	Jonathan	GG-Group	GG-Group	
Simms	Bill	NVIDIA	NVIDIA	X
Sommers	Scott	Molex	Molex	
Su	Charles	Huawei	Huawei	
Sun	Wensheng	Marvell	Marvell	X
Sun	Yi	OFS	OFS	
Suzuki	Yasuo	KDPOF Japan	KDPOF	X
Swanson	Steve	Corning Inc.	Corning Inc.	X
Takahashi	Ryutaro	Senko	Senko	
Takahashi	Satoshi	POF Promotion	POF Promotion	X
Takahashi	Tadashi	Nitto Denko Corporation	Nitto Denko Corporation	X
Takayama	Kazuya	Nitto Denko Corporation	Nitto Denko Corporation	X
Tan	I-Hsing	Broadcom	Broadcom	
Tamada	Tomohiko	JAE	JAE	
Theuerkom	Thomas	Corning	Corning	
Theodoras	James	HG Genuine	HG Genuine	
Torres	Luisma	KDPOF	KDPOF	X
Tsujita	Yuichi	Nitto Denko Corporation	Nitto Denko Corporation	X
Tsuzaki	Nozomi	Independent	Independent	X
Ueno	Yuto	Sumitomo	Sumitomo	X
Vanderlaan	Paul	UL LLC	UL LLC	
Von Vangerow	Christian	TE	TE	X
Voss	Bob	Panduit	Panduit	

Walsh	Thomas	KDPOF	KDPOF	
WATANABE	Yuji	AGC	AGC	X
Wendt	Mattias	Signify	Signify	
Wienckowski	Natalie	General Motors	General Motors	X
Withey	James	Fluke	Fluke	
Wiesner	Michael	Trumpf	Trumpf	
Xu	Dayin	Rockwell Automation	Rockwell Automation	
Xu	Xing	Huawei	Huawei	X
Yamada	Osamu	Yazaki	Yazaki	
Yang	Zhiping	Waymo	Waymo	
Yang	Yumeng	Huawei	Huawei	
Yasui	Hideshi	AGC	AGC	X
Yonemura	Masatoshi	NITech	NITech	
Yonezawa	Kenji	AGC	AGC	
Young	James	Commscope	Commscope	
Yurtin	John	APTIV	APTIV	
Zhang	Sen	Huawei	Huawei	
Zhang	Tingting	Huawei	Huawei	
Zhiwei	Yang	ZTE	ZTE	
Zhong	Qiwen	Huawei	Huawei	
Zhu	Liang	Marvell	Marvell	

## Tuesday, 30th November 2021, 12:00 (noon) UTC

The meeting was called to order at approximately 12:02 UTC Tuesday 30th November 2021  
Chaired by Robert Grow, IEEE P802.3cz Task Force Chair.

Mr. Grow presented *Agenda and General Information*  
([https://www.ieee802.org/3/cz/public/30\\_nov\\_2021/Agenda\\_3cz\\_01\\_301121.pdf](https://www.ieee802.org/3/cz/public/30_nov_2021/Agenda_3cz_01_301121.pdf)).

Mr. Grow presented the agenda for the meeting. There were changes proposed, and no objections, so the agenda was approved by unanimous consent.

Mr. Grow asked for corrections to the November plenary minutes. There were no corrections, so the November plenary minutes were approved by unanimous consent.

Mr. Grow asked the audience if there was anybody from the press. No one responded to the call.

Mr. Grow issued the call for essential patent claims. No one responded to the call. He also presented the slides on the IEEE Copyright Policy and participation guidelines.

Mr. D'Ambrosia asked to present *IEEE P802.3cz Splitting a PAR – The Path Forward*  
([https://www.ieee802.org/3/cz/public/30\\_nov\\_2021/dambrosia\\_3cz\\_01\\_301121.pdf](https://www.ieee802.org/3/cz/public/30_nov_2021/dambrosia_3cz_01_301121.pdf)). This presentation informs about the available process to split the PAR. Before beginning, Mr. D'Ambrosia and Mr. Law pointed out that this presentation reflects their personal opinion on how best to move forward, but they are not taking a position on whether the TF should do a PAR split.

Mr. Law noted that it is the 802.3 WG that makes such decisions and where consensus must be determined.

After the presentation, multiple participants asked questions about what it takes to have a different PHY, distinct identity, the existence or not of 850nm and OM3 proposal, a possible wideband specification, and the differences between implementation and specification, among others.

Mr. D'Ambrosia said that he is struggling with the idea of considering two PHYs as distinct if they only have a different wavelength. Mr. Law supported him.

Mr. Grow noted that there are Ethernet implementations on the market that support multiple PHY types, such as those that implement the 10/100/1000 Mb/s 802.3 Ethernet specifications on laptops and computers in a single device, but such devices are implementation choices and are not specified in the standard.

Mr. Law said that he thought it was acceptable to have a transmitter specification for a wide range of frequencies and a corresponding receiver specification for the same wide range of frequencies.

Ms. Haasz in response to Mr. D'Ambrosia's request noted that for the PAR split example given in the presentation, IEEE 802.3cn was approved on 7 November 2019 and the split project IEEE 802.3ct was approved on 16 June 2021.

In response to a direct question about what difference in timelines justified a PAR split, he replied that his personal opinion was delaying a project for one year justified a PAR split. He also noted his personal opinion that we have been delaying already for some time.

Mr. D'Ambrosia said that hijacking a project to specify something not covered in the initial project documents not acceptable, and that there were various alternatives including splitting a PAR to do such work not originally included in the project documents; and asked that this be taken into consideration.

Mr. D'Ambrosia, said that he will propose straw polls to sense TF support for a PAR split for the next 802.3cz meeting (14 December).

Mr. Swanson said that he will contribute a presentation including an initial PAR split proposal for the next 802.3cz meeting (14 December).

Mr. Grow reviewed next meetings in the presented *Agenda and General Information* ([https://www.ieee802.org/3/cz/public/30\\_nov\\_2021/Agenda\\_3cz\\_01\\_301121.pdf](https://www.ieee802.org/3/cz/public/30_nov_2021/Agenda_3cz_01_301121.pdf)).

Mr. Grow announced that the TF will not meet on 28 December due to the year-end holidays.

Mr. Grow noted that a meeting fee (700\$ to 1000\$) is required to participate in the next March 2022 802.3 Plenary meeting, regardless if it is in person or virtual.

Mr. Swanson commented on the meeting fees, which he considers to be too high. He also commented that he does not feel that there will be a high number of people attending in person, as the meeting fee is the same regardless of whether it is face-to-face or virtual and virtual attendance will be less costly.

Mr. Grow noted Mr. Swanson's comments, and noted that these fees have already been decided by the IEEE 802 Executive Committee.

Having exhausted the items to discuss, the meeting was recessed at approximately 13:50 UTC.

Recording secretary: Luisma Torres.